Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- 40V, 10A, $R_{DS(ON).max}$=16.5mΩ@V_{GS}=10V
- Improved dv/dt capability
- Fast switching
- Green device available

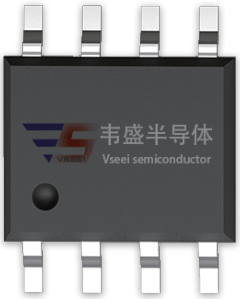
Applications

- Motor Drives
- UPS
- DC-DC Converter

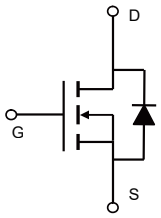
Product Summary

V_{DSS}	40V
$R_{DS(on).max}$@ V_{GS}=10V	16.5mΩ
I_D	10A

SOP-8 Pin Configuration



SOP-8



Schematic

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	40	V
Continuous drain current (T_A = 25°C)	I_D	10	A
Continuous drain current (T_A = 100°C)		5.3	A
Pulsed drain current[1)]	I_{DM}	40	A
Gate-Source voltage	V_{GSS}	±20	V
Power Dissipation (T_A = 25°C)	P_D	2	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking
VSM10N04-S8	SOP-8	VSM10N04-S8

Electrical Characteristics

T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0 V, I_D=250uA	40	---	---	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250uA	1.0	1.5	2.0	V
Drain-source leakage current	I_{DSS}	V_{DS}=40 V, V_{GS}=0 V, T_J = 25°C	---	---	1	μA
		V_{DS}=32 V, V_{GS}=0 V, T_J = 125°C	---	---	10	μA
Gate leakage current, Forward	I_{GSSF}	V_{GS}=20 V, V_{DS}=0V	---	---	100	nA
Gate leakage current, Reverse	I_{GSSR}	V_{GS}=-20 V, V_{DS}=0V	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=10A	---	13.5	16.5	mΩ
		V_{GS}=4.5 V, I_D=5A	---	18	23	mΩ
Forward transconductance	g_{fs}	V_{DS} =5 V , I_D=10A	---	35	---	S
Dynamic characteristics						
Input capacitance	C_{iss}	V_{DS} = 20 V, V_{GS} = 0 V, F = 1MHz	---	1060	---	pF
Output capacitance	C_{oss}		---	126	---	
Reverse transfer capacitance	C_{rss}		---	101	---	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 20V,V_{GS}=10V, I_D =10A	---	11.8	---	ns
Rise time	t_r		---	18.0	---	
Turn-off delay time	$t_{d(off)}$		---	46.6	---	
Fall time	t_f		---	15.7	---	
Gate charge characteristics						
Gate to source charge	Q_{gs}	V_{DS}=20V, I_D=10A, V_{GS}= 10 V	---	5.8	---	nC
Gate to drain charge	Q_{gd}		---	3.0	---	
Gate charge total	Q_g		---	18.1	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I_S		---	---	10	A
Pulsed Source Current	I_{SM}		---	---	40	A
Diode Forward Voltage[2)]	V_{SD}	V_{GS}=0V, I_S=10A, T_J=25℃	---	---	1.2	V
Reverse Recovery Time	t_{rr}	I_S=10A,di/dt=100A/us, T_J=25℃	---	30.4	---	ns
Reverse Recovery Charge	Q_{rr}		---	9.6	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: Pulse Test：Pulse Width ≤300μs, Duty Cycle≤2%.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

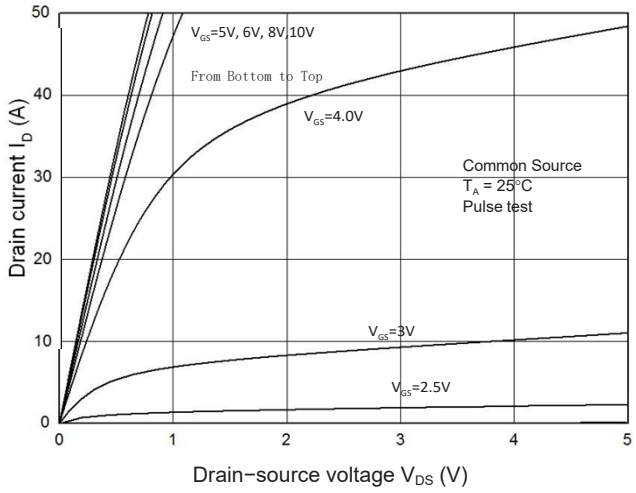


Figure 2. Transfer Characteristics

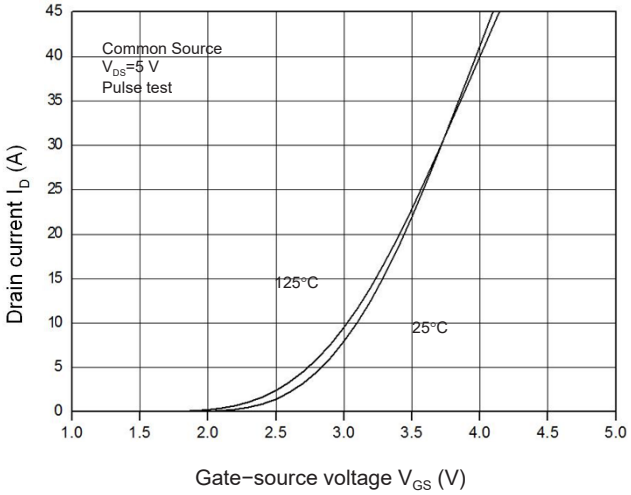


Figure 3. Capacitance Characteristics

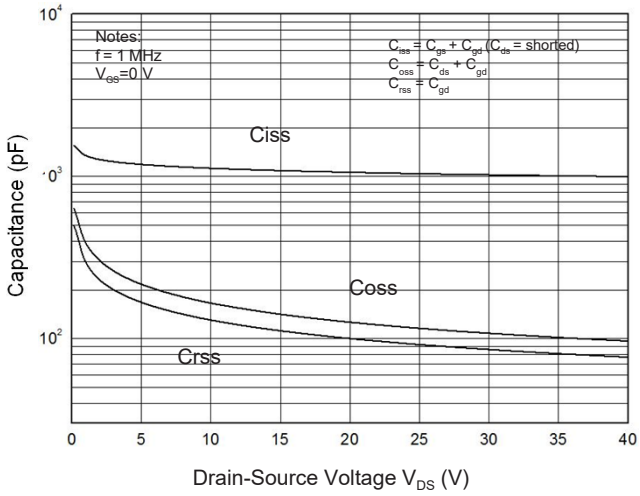


Figure 4. Gate Charge Waveform

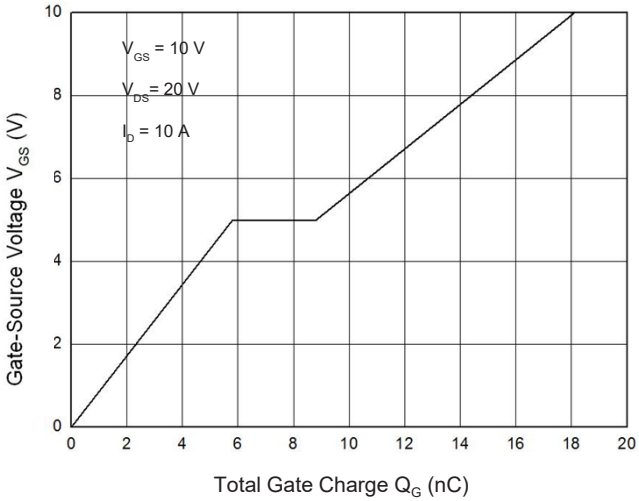


Figure 5. Body-Diode Characteristics

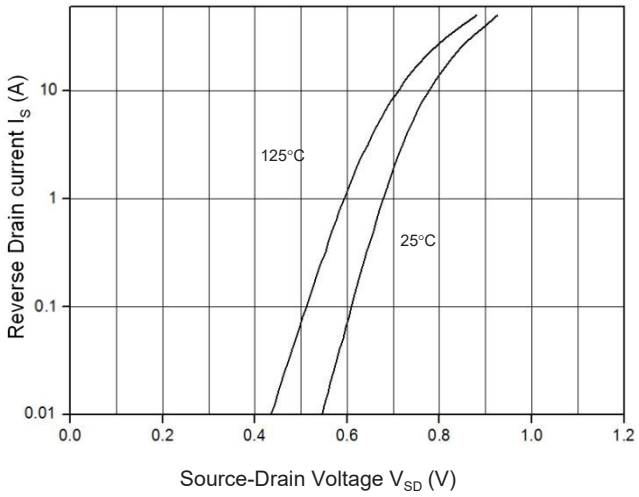


Figure 6. Rdson-Drain Current

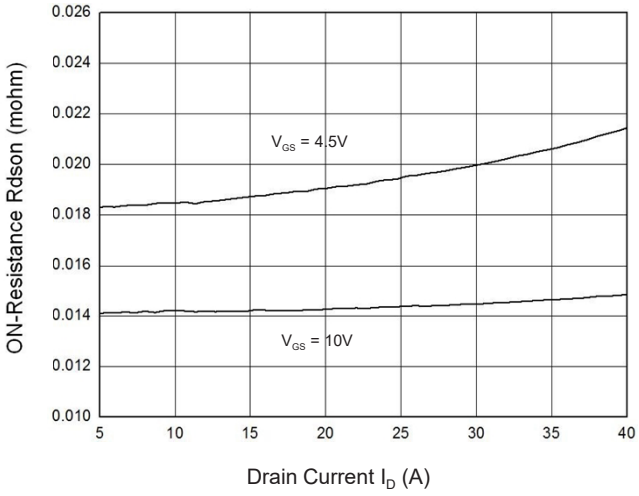


Figure 7. Rdson-Junction Temperature(℃)

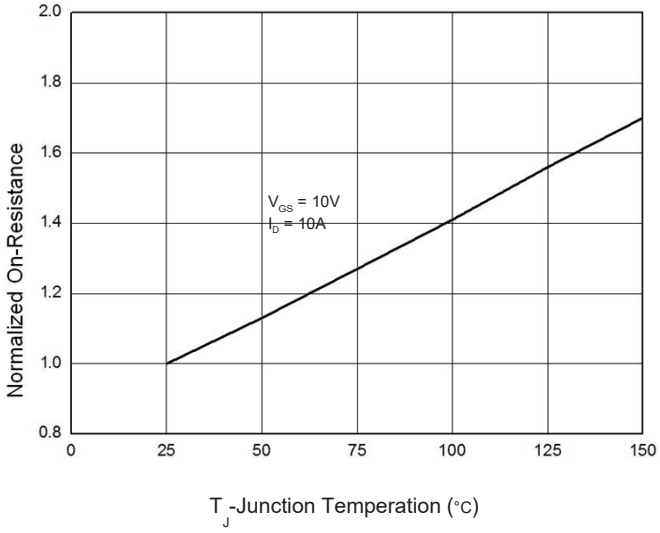


Figure 8. Maximum Safe Operating Area

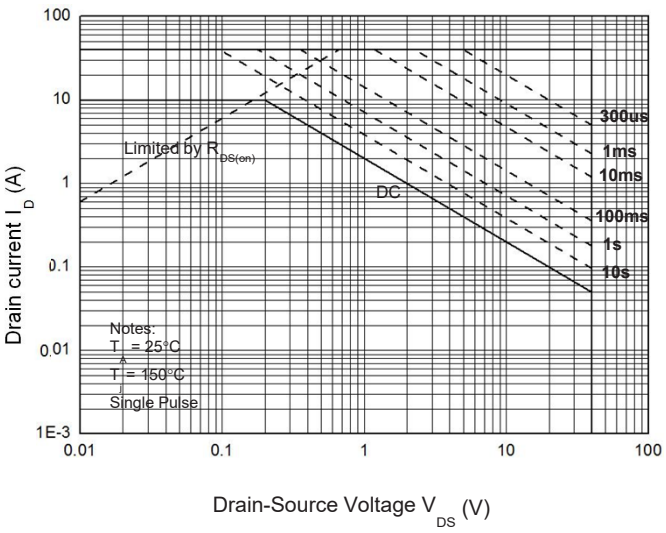
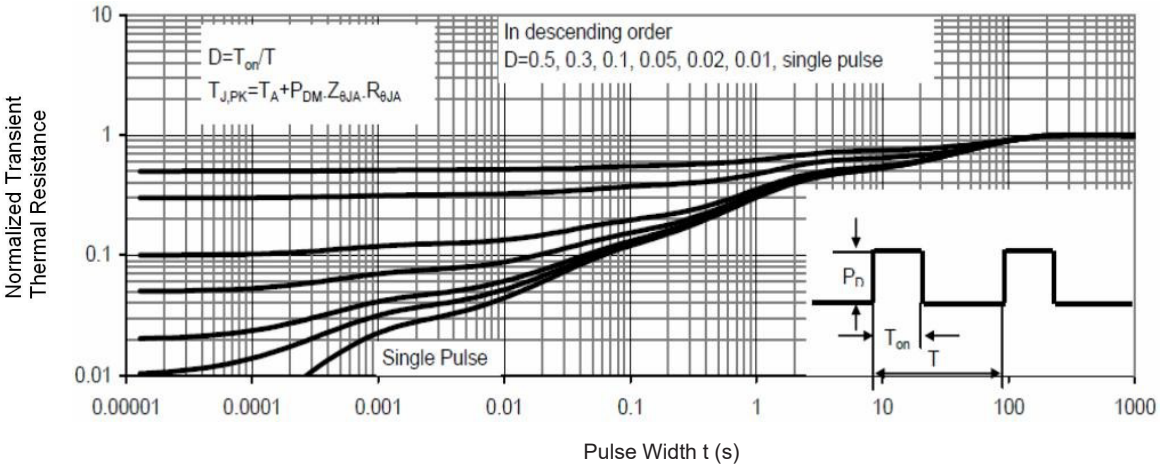


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)



Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

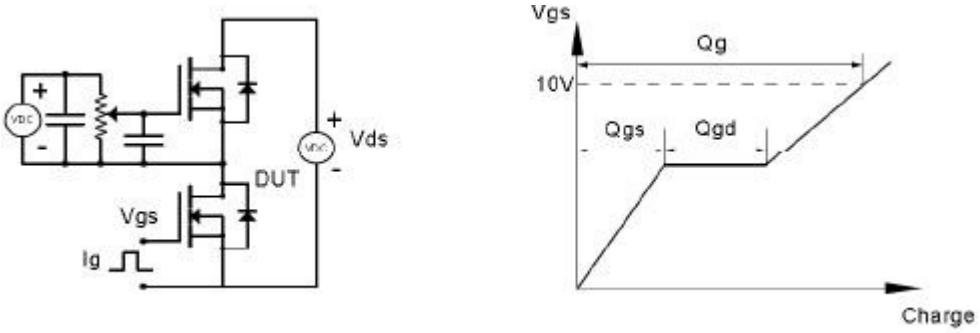


Figure 9. Resistive Switching Test Circuit & Waveforms

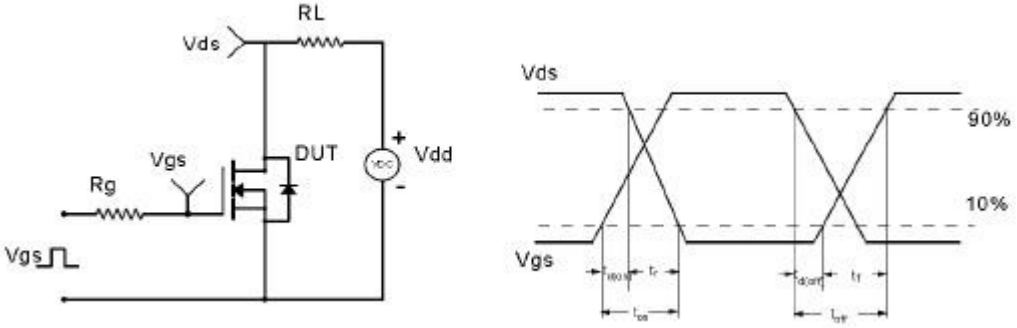


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

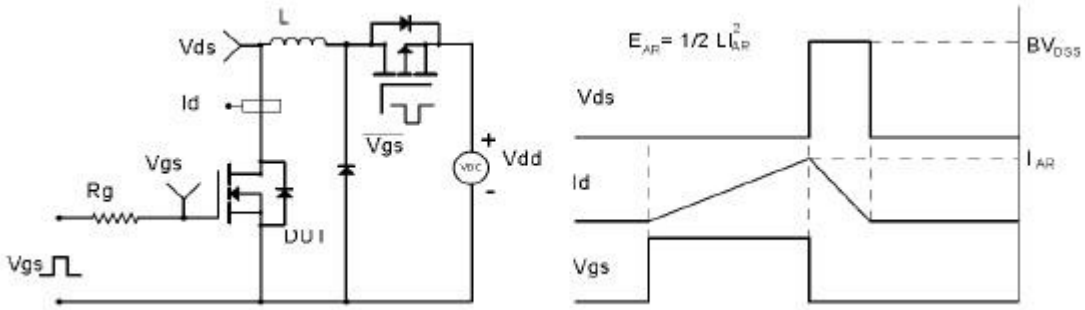


Figure 11. Diode Recovery Circuit & Waveform